

**Notice of References Cited**

Application/Control No.

09/692,527

Applicant(s)/Patent Under  
Reexamination  
WEIDMAN ET AL.

Examiner

Christy L. Novacek

Art Unit

2822

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**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-6,140,221	10-2000	Annapragada et al.	438/622
	B	US-5,926,740	07-1999	Forbes et al.	438/763
	C	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Xu, et al., "BLOk - A Low-k Dielectric Barrier/Etch Stop Film for Copper Damascene Applications", Interconnect Technology, 1999, IEEE International Conference, pp. 109-111, May 1999
	V	Loboda et al., "Plasma-enhanced chemical vapor deposition of a-SiC:H films from organosilicon precursors", J. Vac. Sci. Technol. A, Vol. 12(1), pp. 90-96, Jan/Feb 1994
	W	Loboda et al., "Deposition of Low-k Dielectric Films Using Trimethylsilane", Proceedings of the Electrochemical Society Symposia on Electrochemical Processing In ULSI Fabrication I and Interconnect and Contact Metallization, Vol. 98-6, pp. 145-152, 1998
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.